

PCN Number:	20170926001	PCN Date:	September 28, 2017
Title:	Datasheet for LMH1228		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



LMH1228

SNLS568B – MARCH 2017 – REVISED SEPTEMBER 2017

Changes from Revision A (July 2017) to Revision B

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• Changed NTps _{max} test condition max from 6 GHz to 50 MHz and < 20 mVp-p NOM to < 10 mVp-p	5
• Changed t _{R_F_SDI} minimum SD rise/fall time from 390 ps to 400 ps due to incorrect default settings.....	9
• Changed typical t _R /t _F of OUT0 from 35 ps to 45 ps	10
• Added PRBS10 pattern to clarify AJ _{CD} and TMJ _{CD} Test Condition	10
• Added SMBUS SCL minimum frequency per SMBus 2.0 specifications	11
• Added Figure 1 to clarify definition of SMBus Timing Parameters in <i>Recommended SMBus Interface Timing Specifications</i>	12
• Added typical characteristic curves for OUT0 VOD and de-emphasis vs. LMH1228 register settings	14
• Added default internal pullup and pulldown settings for 2-level strap pins in Figure 20	27
• Added clarification in Table 11 regarding reclocker behavior when used with non-SDI data rates	28
• Added mechanical, thermal pad, and land pattern drawings to the <i>Package Option Addendum</i>	38

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMH1228	SNLS568A	SNLS568B

The datasheet is considered "custom", for that reason; the document is not available on the TI website. Please contact the TI Customer Quality Engineer (CQE) for a copy of the datasheet.

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

LMH1228RTVR	LMH1228RTVT	
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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